

ABSTRACT OF THE DISCLOSURE

A lead frame and a semiconductor chip package including a side ring pad are disclosed. In the present invention, According to the present invention, a lead frame is provided with a die pad on which a semiconductor chip is mounted. A plurality of inner leads is electrically interconnected to corresponding electrode pads by a plurality of bonding wires. A side ring pad is disposed around the die pad and between the die pad and the inner leads. A tie bar connects the die pad and the side ring pad. The electrode pads include power electrode pads that are electrically interconnected to the side ring pad by power bonding wires. The bonding wires may include first link bonding wires connected between the electrode pads and the metal pads and second link bonding wires connected between the metal pads and the inner leads.

With the present invention, grounding capacity and high frequency characteristics of a semiconductor chip package are improved and ground noise is reduced. Further, the inner leads can be placed more freely and flexibility of the bonding wires is enhanced. Moreover, it is possible to meet the fine lead and high-pin-count requirements that are required of modern packages at lower cost.